Dual 2-to-4 Decoder/ Demultiplexer

The MC74VHC139 is an advanced high speed CMOS 2-to-4 decoder/ demultiplexer fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

When the device is enabled (\overline{E} = low), it can be used for gating or as a data input for demultiplexing operations. When the enable input is held high, all four outputs are fixed high, independent of other inputs.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The inputs tolerate voltages up to $7~\rm V$, allowing the interface of $5~\rm V$ systems to $3~\rm V$ systems.

- High Speed: $t_{PD} = 5.0 \text{ ns}$ (Typ) at $V_{CC} = 5 \text{ V}$
- Low Power Dissipation: $I_{CC} = 4 \mu A$ (Max) at $T_A = 25^{\circ}C$
- High Noise Immunity: $V_{NIH} = V_{NIL} = 28\% V_{CC}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2 V to 5.5 V Operating Range
- Low Noise: V_{OLP} = 0.8 V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: Human Body Model > 2000 V;

Machine Model > 200 V

- Chip Complexity: 100 FETs or 25 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant



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MARKING DIAGRAMS

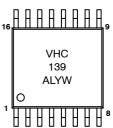


SOIC-16 D SUFFIX CASE 751B



TSSOP-16 DT SUFFIX CASE 948F

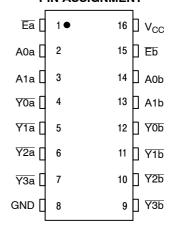




A = Assembly Location

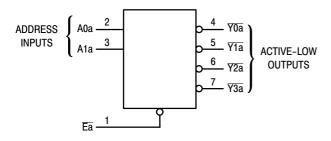
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.



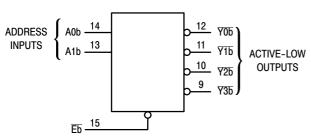


Table 1. FUNCTION TABLE

Inputs			Outputs			
E	A1	A0	Y0	<u>Y1</u>	<u>Y2</u>	<u></u> 73
Н	Х	Х	Н	Н	Н	Н
L	L	L	L	Н	Н	Н
L	L	Н	Н	L	Н	Н
L	Н	Ĺ	Н	Н	L	Н
L	Н	Н	Н	Н	Н	L

Figure 1. Logic Diagram

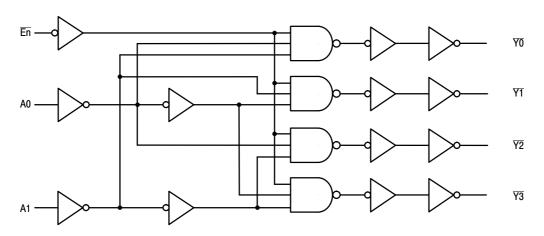


Figure 2. Expanded Logic Diagram (1/2 of Device)

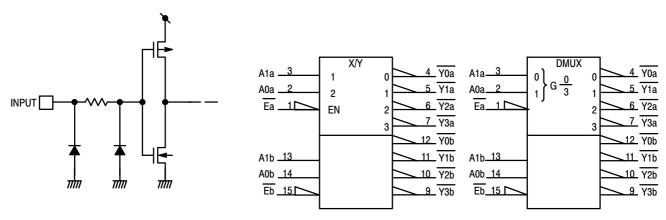


Figure 3. Input Equivalent Circuit

Figure 4. IEC Logic Diagram

MAXIMUM RATINGS

Symbol	Paramete	r	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{in}	DC Input Voltage	-0.5 to +7.0	V	
V _{out}	DC Output Voltage	-0.5 to V _{CC} + 0.5	V	
I _{IK}	Input Diode Current	-20	mA	
lok	Output Diode Current	±20	mA	
I _{out}	DC Output Current, per Pin	±25	mA	
I _{CC}	DC Supply Current, V _{CC} and GI	±75	mA	
P _D	Power Dissipation in Still Air,	SOIC Packages [†] TSSOP Package [†]	500 450	mW
T _{stg}	Storage Temperature		-65 to +150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND $\leq (V_{in} \mbox{ or } V_{out}) \leq V_{CC}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

†Derating - SOIC Packages: - 7 mW/°C from 65° to 125°C TSSOP Package: - 6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	DC Supply Voltage		2.0	5.5	٧
V _{in}	DC Input Voltage		0	5.5	٧
V _{out}	DC Output Voltage		0	V _{CC}	٧
T _A	Operating Temperature		-55	+125	°C
t _r , t _f	Input Rise and Fall Time V _C (Figure 3) V _C	$_{CC} = 3.3 \text{ V} \pm 0.3 \text{V}$ $_{CC} = 5.0 \text{ V} \pm 0.5 \text{V}$	0	100 20	ns/V

The θ_{JA} of the package is equal to 1/Derating. Higher junction temperatures may affect the expected lifetime of the device per the table and figure below.

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature (°C)	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

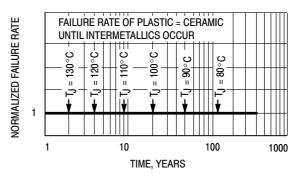


Figure 5. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			Vcc	Т	A = 25°	С	T _A = ≤	85°C	T _A = ≤	125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V _{IL}	Maximum Low-Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V _{OH}	Minimum High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
	$V_{IN} = V_{IH}$ or V_{IL}	$\begin{aligned} V_{IN} &= V_{IH} \text{ or } V_{IL} \\ I_{OH} &= -4 \text{ mA} \\ I_{OH} &= -8 \text{ mA} \end{aligned}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V _{OL}	Maximum Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu A$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
	$V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 4$ mA $I_{OL} = 8$ mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Maximum Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			± 0.1		± 1.0		± 1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			4.0		40.0		40.0	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_f = t_f = 3.0$ ns)

			Т	T _A = 25°C		T _A = - 40 to 85°C				
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay, A to Y	$V_{CC} = 3.3 \pm 0.3 \ VC_L = 15 \ pF$ $C_L = 50 \ pF$		7.2 9.7	11.0 14.5	1.0 1.0	13.0 16.5	1.0 1.0	13.0 16.5	ns
	7.01	$V_{CC} = 5.0 \pm 0.5 \text{ VC}_{L} = 15 \text{ pF}$ $C_{L} = 50 \text{ pF}$		5.0 6.5	7.2 9.2	1.0 1.0	8.5 10.5	1.0 1.0	8.5 10.5	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, E to Y	$V_{CC} = 3.3 \pm 0.3 \ VC_L = 15 \ pF$ $C_L = 50 \ pF$		6.4 8.9	9.2 12.7	1.0 1.0	11.0 14.5	1.0 1.0	11.0 14.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ VC}_{L} = 15 \text{ pF}$ $C_{L} = 50 \text{ pF}$		4.4 5.9	6.3 8.3	1.0 1.0	7.5 9.5	1.0 1.0	7.5 9.5	
C _{IN}	Maximum Input Capacitance			4	10		10		10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (1)	26	pF

^{1.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/2 (per decoder). C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

SWITCHING WAVEFORMS

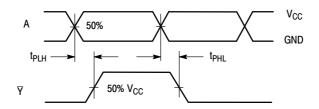


Figure 6.

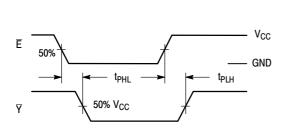
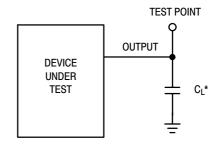


Figure 7.



*Includes all probe and jig capacitance

Figure 8. Test Circuit

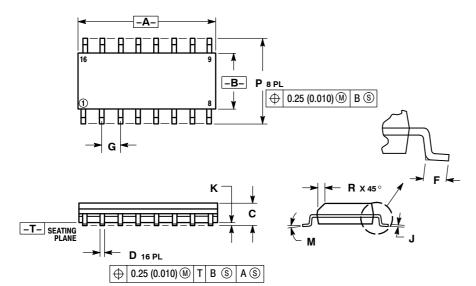
ORDERING INFORMATION

Device	Package	Shipping [†]
MC74VHC139DR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC74VHC139DTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

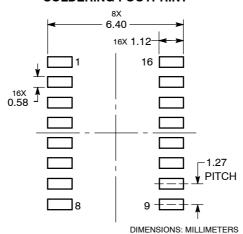
SOIC-16 CASE 751B-05 ISSUE K



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

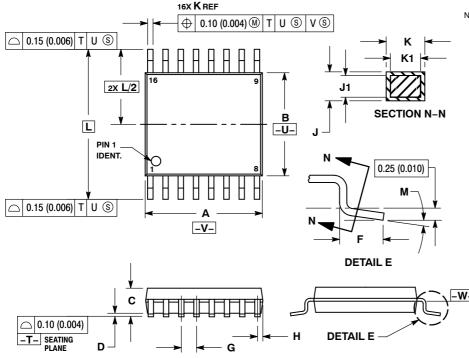
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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PACKAGE DIMENSIONS

TSSOP-16 CASE 948F-01 **ISSUE B**



NOTES:

- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.

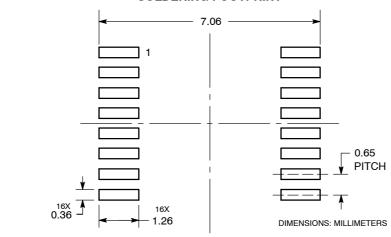
 CONTROLLING DIMENSION: MILLIMETER.

 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT
- EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE
- DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6. TERMINAL NUME REFERENCE ONLY. TERMINAL NUMBERS ARE SHOWN FOR
- DIMENSION A AND B ARE TO BE

PETE	RMINED MILLIN	AT DATU IETERS	IM PLANE -W INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026	BSC	
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
Ĺ	6.40 BSC		0.252 BSC		
М	0°	8 °	0°	8 °	

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